BGU7005

SiGe:C Low Noise Amplifier MMIC for GPS, GLONASS, Galileo and Compass

Rev. 6 — 18 January 2017

Product data sheet

1. Product profile

1.1 General description

The BGU7005 is, also known as the GPS1101M, a Low Noise Amplifier (LNA) for GNSS receiver applications in a plastic leadless 6-pin, extremely small SOT886 package. The BGU7005 requires only one external matching inductor and one external decoupling capacitor.

The BGU7005 adapts itself to the changing environment resulting from co-habitation of different radio systems in modern cellular handsets. It has been designed for low power consumption and optimal performance when jamming signals from co-existing cellular transmitters are present. At low jamming power levels it delivers 16.5 dB gain at a noise figure of 0.85 dB. During high jamming power levels, resulting for example from a cellular transmit burst, it temporarily increases its bias current to improve sensitivity.

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Therefore care should be taken during transport and handling.

1.2 Features and benefits

- Covers full GNSS L1 band, from 1559 MHz to 1610 MHz
- Noise figure (NF) = 0.85 dB
- Gain 16.5 dB
- High input 1 dB compression point P_{i(1dB)} of -11 dBm
- High out of band IP3_i of 9 dBm
- Supply voltage 1.5 V to 3.1 V
- Power-down mode current consumption < 1 μA</p>
- Optimized performance at low supply current of 4.5 mA
- Integrated matching for the output
- Requires only one input matching inductor and one supply decoupling capacitor
- Input and output DC decoupled
- ESD protection on all pins (HBM > 2 kV)
- Integrated temperature stabilized bias for easy design
- Small 6-pin leadless package 1 mm × 1.45 mm × 0.5 mm
- 110 GHz transit frequency SiGe:C technology



1.3 Applications

LNA for GPS, GLONASS, Galileo and Compass (BeiDou) in smart phones, feature phones, tablet PCs, Personal Navigation Devices, Digital Still Cameras, Digital Video Cameras, RF Front End modules, complete GPS chipset modules and theft protection (laptop, ATM).

1.4 Quick reference data

Table 1.Quick reference data

f = 1559 MHz to 1610 MHz; $V_{CC} = 1.8 \text{ V}$; $P_i < -40 \text{ dBm}$; $T_{amb} = 25 \text{ °C}$; input matched to 50 Ω using a 5.6 nH inductor; unless otherwise specified.

	· ·						
Symbol	Parameter	Conditions		Min	Тур	Мах	Unit
V_{CC}	supply voltage	RF input AC coupled		1.5	-	3.1	V
I _{CC}	supply current	$V_{\text{ENABLE}} \geq 0.8 \ \text{V}$					
		P _i < -40 dBm		3.2	4.5	5.7	mA
		$P_i = -20 \text{ dBm}$		8.1	11.6	14.4	mA
G _p	power gain	P _i < -40 dBm, no jammer		14	16.5	19	dB
		$P_i = -20 \text{ dBm}$, no jammer		15	17.5	20	dB
NF	noise figure	P _i < -40 dBm, no jammer	[1]	-	0.85	1.2	dB
		P _i < -40 dBm, no jammer	[2]	-	0.9	1.3	dB
		$P_i = -20 \text{ dBm}$, no jammer		-	1.2	1.6	dB
P _{i(1dB)}	input power at 1 dB gain compression	f = 1575 MHz					
		V _{CC} = 1.5 V		-15	-12	-	dBm
		V _{CC} = 1.8 V		-14	-11	-	dBm
		V _{CC} = 2.85 V		-11	-8	-	dBm
IP3 _i	input third-order intercept point	f = 1.575 GHz					
		V _{CC} = 1.5 V	[3]	5	8	-	dBm
		V _{CC} = 1.8 V	[3]	5	9	-	dBm
		V _{CC} = 2.85 V	[3]	5	12	-	dBm

[1] PCB losses are subtracted.

[2] Including PCB losses.

[3] $f_1 = 1713 \text{ MHz}; f_2 = 1851 \text{ MHz}; P_1 = P_2 = -30 \text{ dBm}.$

2. Pinning information

Pin	Description	Simplified outline Gra	aphic symbol
1	GND		
2	GND		4 5
3	RF_IN		3 - 6
4	V _{CC}		
5	ENABLE		2 1 sym129
6	RF_OUT		0,11120

3. Ordering information

Table 3. Ordering information							
Type number	Package	Package					
	Name	Description	Version				
BGU7005	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 \times 1.45 \times 0.5 mm	SOT886				

4. Marking

Table 4. Marking codes	
Type number	Marking code
BGU7005	AC

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage	RF input AC coupled	-0.5	5.0	V
V _{ENABLE}	voltage on pin ENABLE	$V_{\text{ENABLE}} < V_{\text{CC}} + 0.6$	<u>[2]</u> –0.5	5.0	V
$V_{RF_{IN}}$	voltage on pin RF_IN	DC; $V_{RF_{IN}} < V_{CC} + 0.6$	<u>[2][3]</u> –0.5	5.0	V
V_{RF}_{OUT}	voltage on pin RF_OUT	DC; $V_{RF_{OUT}} < V_{CC} + 0.6$	[2][3] –0.5	5.0	V
Pi	input power		-	0	dBm
P _{tot}	total power dissipation	$T_{sp} \le 130 \ ^{\circ}C$	<u>[1]</u>	55	mW
T _{stg}	storage temperature		-65	150	°C
Tj	junction temperature		-	150	°C
V _{ESD}	electrostatic discharge voltage	Human Body Model (HBM); According JEDEC standard 22-A114E	-	4	kV
		Charged Device Model (CDM); According JEDEC standard 22-C101B	-	1	kV

[1] T_{sp} is the temperature at the soldering point of the emitter lead.

[2] Warning: due to internal ESD diode proctection, the applied DC voltage should not exceed V_{CC} + 0.6 and shall not exceed 5.0 V in order to avoid excess current.

[3] The RF input and RF output are AC coupled through internal DC blocking capacitor.

6. Thermal characteristics

Table 6.	Thermal characteristics			
Symbol	Parameter	Conditions	Тур	Unit
R _{th(j-sp)}	thermal resistance from junction to solder point		225	K/W

7. Characteristics

Table 7. Characteristics

f = 1559 MHz to 1610 MHz; $V_{CC} = 1.8 \text{ V}$; $V_{ENABLE} \ge 0.8 \text{ V}$; $P_i < -40 \text{ dBm}$; $T_{amb} = 25 \text{ °C}$; input matched to 50 Ω using a 5.6 nH inductor; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Uni
V _{CC}	supply voltage	RF input AC coupled	1.5	-	3.1	V
I _{CC} supply current		$V_{\text{ENABLE}} \ge 0.8 \text{ V}$				
		P _i < -40 dBm	3.2	4.5	5.7	mΑ
		$P_i = -20 \text{ dBm}$	8.1	11.6	14.4	mΑ
		$V_{\text{ENABLE}} \leq 0.35 \text{ V}$	-	-	1	μΑ
T _{amb}	ambient temperature		-40	+25	+85	°C
G _p	power gain	T _{amb} = 25 °C				
		P _i < −40 dBm, no jammer	14	16.5	19	dB
		$P_i = -20 \text{ dBm}$, no jammer	15	17.5	20	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 850 \text{ MHz}$	15	17.5	20	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 1850 \text{ MHz}$	15	17.5	20	dB
		$-40~^{\circ}C \leq T_{amb} \leq +85~^{\circ}C$				
		P _i < −40 dBm, no jammer	13	-	20	dB
		$P_i = -20 \text{ dBm}$, no jammer	14	-	21	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 850 \text{ MHz}$	14	-	21	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 1850 \text{ MHz}$	14	-	21	dB
RL _{in}	input return loss	P _i < -40 dBm	5	8	-	dB
		$P_i = -20 \text{ dBm}$	6	10	-	dB
RL _{out}	output return loss	P _i < -40 dBm	10	20	-	dB
		$P_i = -20 \text{ dBm}$	10	14	-	dB
ISL	isolation		20	23	-	dB
NF	noise figure	T _{amb} = 25 °C				
		P _i < −40 dBm, no jammer	<u>[1]</u> _	0.85	1.2	dB
		P _i < −40 dBm, no jammer	[2] _	0.9	1.3	dB
		$P_i = -20 \text{ dBm}$, no jammer	-	1.2	1.6	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 850 \text{ MHz}$	-	1.1	1.5	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 1850 \text{ MHz}$	-	1.3	1.7	dB
		$-40~^\circ C \leq T_{amb} \leq +85~^\circ C$				
		P _i < −40 dBm, no jammer	-	-	1.7	dB
		$P_i = -20 \text{ dBm}$, no jammer	-	-	1.9	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 850 \text{ MHz}$	-	-	1.8	dB
		$P_{jam} = -20 \text{ dBm}; f_{jam} = 1850 \text{ MHz}$	-	-	2.0	dB

Table 7. Characteristics ... continued

f = 1559 MHz to 1610 MHz; $V_{CC} = 1.8 \text{ V}$; $V_{ENABLE} \ge 0.8 \text{ V}$; $P_i < -40 \text{ dBm}$; $T_{amb} = 25 \text{ °C}$; input matched to 50 Ω using a 5.6 nH inductor; unless otherwise specified.

Symbol	Parameter	Conditions	Mi	n Typ	Max	Unit
P _{i(1dB)}	input power at 1 dB gain compression	f = 1575 MHz				
		V _{CC} = 1.5 V	-1	5 –12	-	dBm
		V _{CC} = 1.8 V	-1	4 –11	-	dBm
		V _{CC} = 2.85 V	-1	1 –8	-	dBm
		f = 806 MHz to 928 MHz				
		V _{CC} = 1.5 V	<u>[3]</u> –1	5 –12	-	dBm
		V _{CC} = 1.8 V	<u>[3]</u> –1	4 –11	-	dBm
		V _{CC} = 2.85 V	<u>[3]</u> –1	4 –11	-	dBm
		f = 1612 MHz to 1909 MHz				
		V _{CC} = 1.5 V	<u>[3]</u> –1	3 –10	-	dBm
		V _{CC} = 1.8 V	<u>[3]</u> –1	2 –9	-	dBm
		V _{CC} = 2.85 V	<u>[3]</u> –1	0 –7	-	dBm
IP3 _i	input third-order intercept point	f = 1.575 GHz				
		V _{CC} = 1.5 V	<u>[4]</u> 5	8	-	dBm
		V _{CC} = 1.8 V	<u>[4]</u> 5	9	-	dBm
		V _{CC} = 2.85 V	<u>[4]</u> 5	12	-	dBm
t _{on}	turn-on time		<u>[5]</u> _	-	2	μS
t _{off}	turn-off time		<u>[5]</u> _	-	1	μS
K	Rollett stability factor		1	-	-	

[1] PCB losses are subtracted.

[2] Including PCB losses.

[3] Out of band.

[4] $f_1 = 1713$ MHz; $f_2 = 1851$ MHz; $P_1 = P_2 = -30$ dBm.

[5] Within 10 % of the final gain.

Table 8.ENABLE (pin 5)

$-40 \text{ °C} \le T_{amb} \le +85 \text{ °C}; 1.5 \text{ V} \le V_{CC} \le 3.1 \text{ V}$	-40	$^{\circ}C \leq T_{amb}$	≤+85	°C; 1	1.5 V	′≤V	′cc ≤	3.1	V	
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V _{ENABLE} (V)	State	
≤ 0.35	OFF	
≥ 0.8	ON	

8. Application information

8.1 GNSS LNA

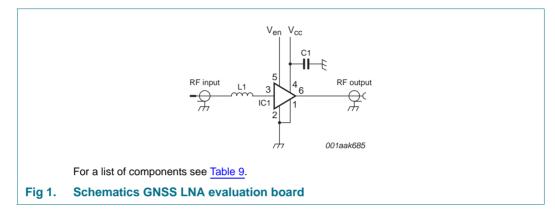
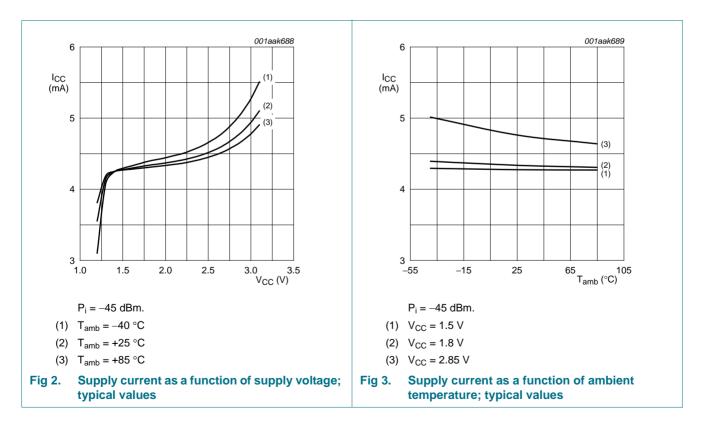
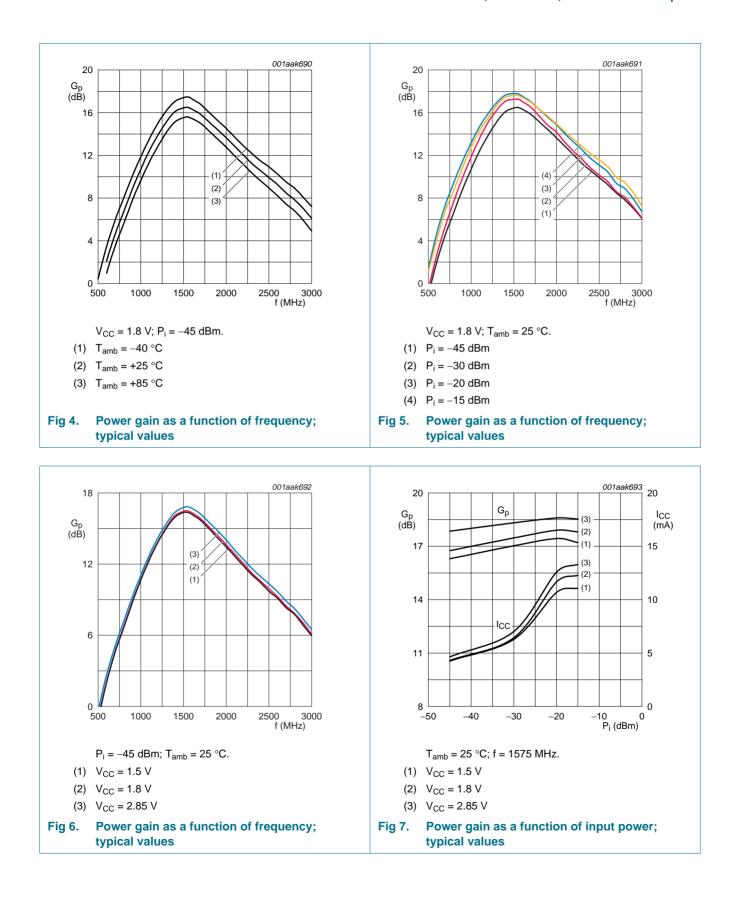


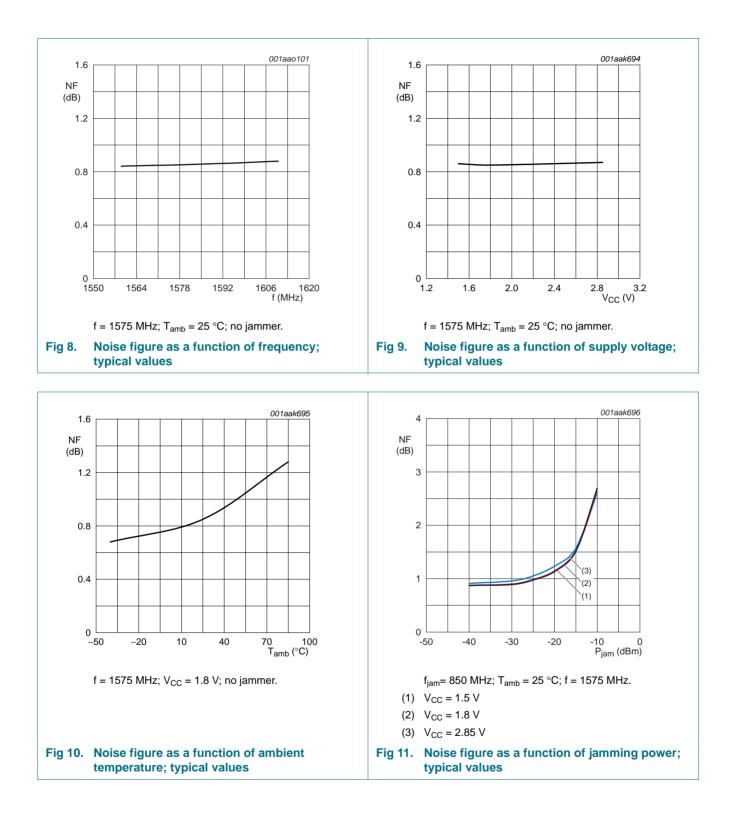
Table 9.List of componentsFor schematics see Figure 1.

Component	Description	Value	Supplier	Remarks
C1	decoupling capacitor	1 nF	various	
IC1	BGU7005	-	NXP	
L1	high quality matching inductor	5.6 nH	Murata LQW15A	





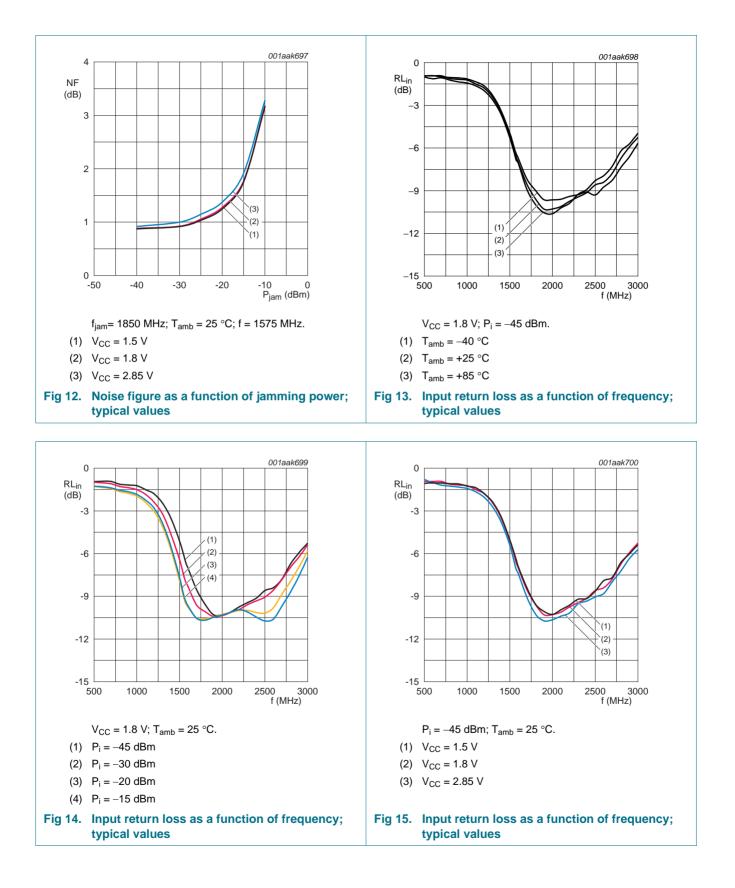
BGU7005

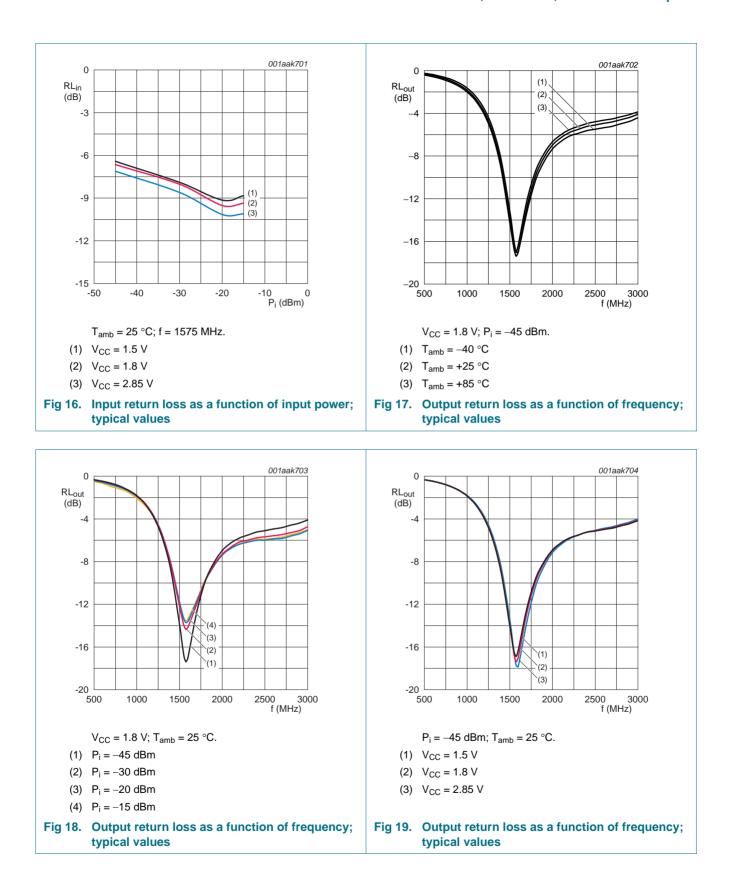


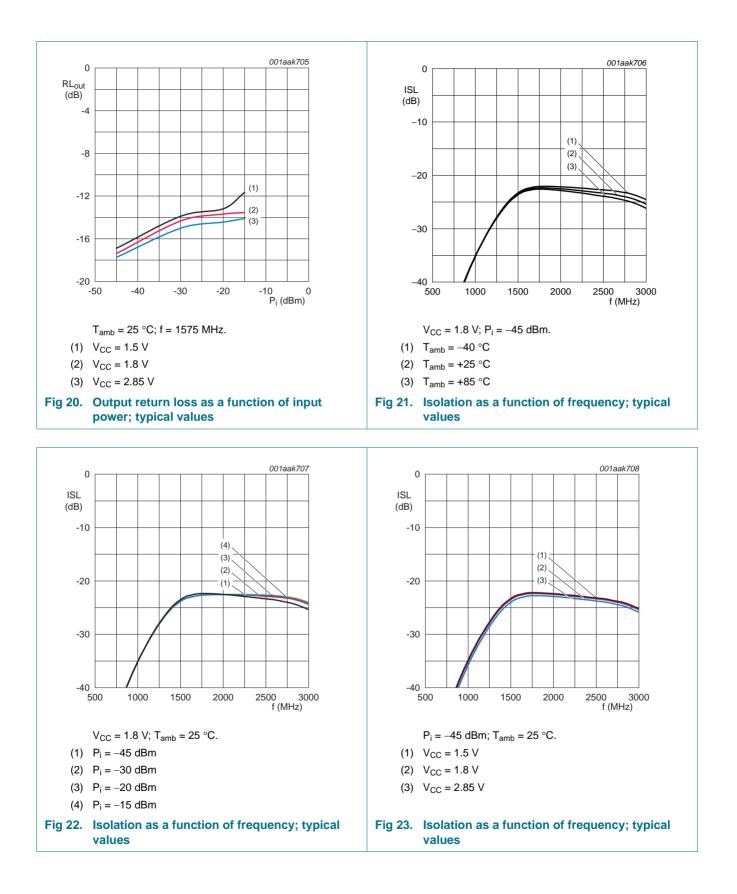
Product data sheet

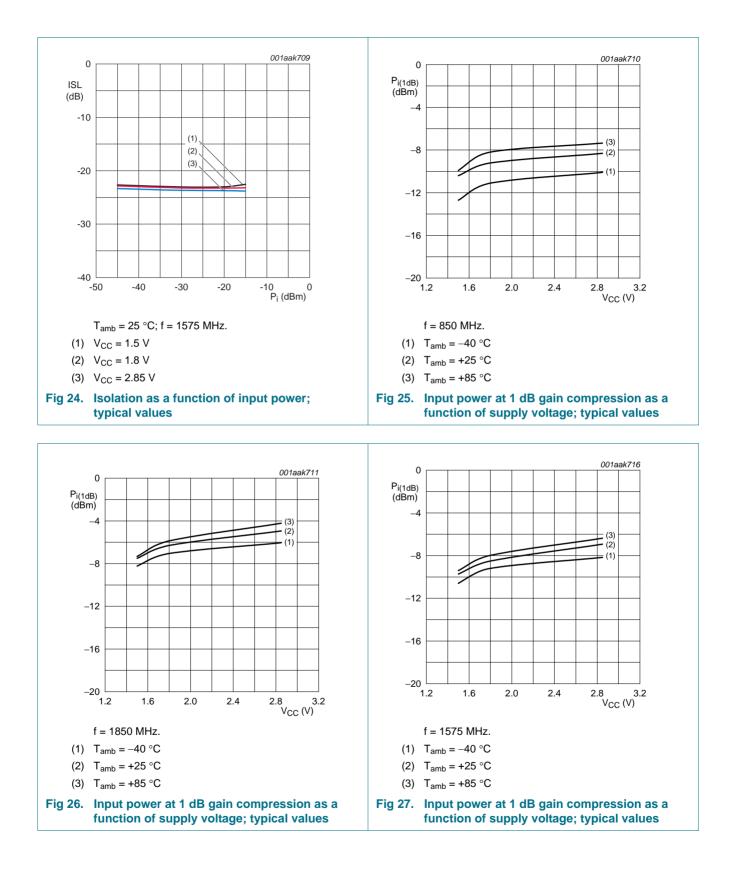
BGU7005

SiGe:C LNA MMIC for GPS, GLONASS, Galileo and Compass



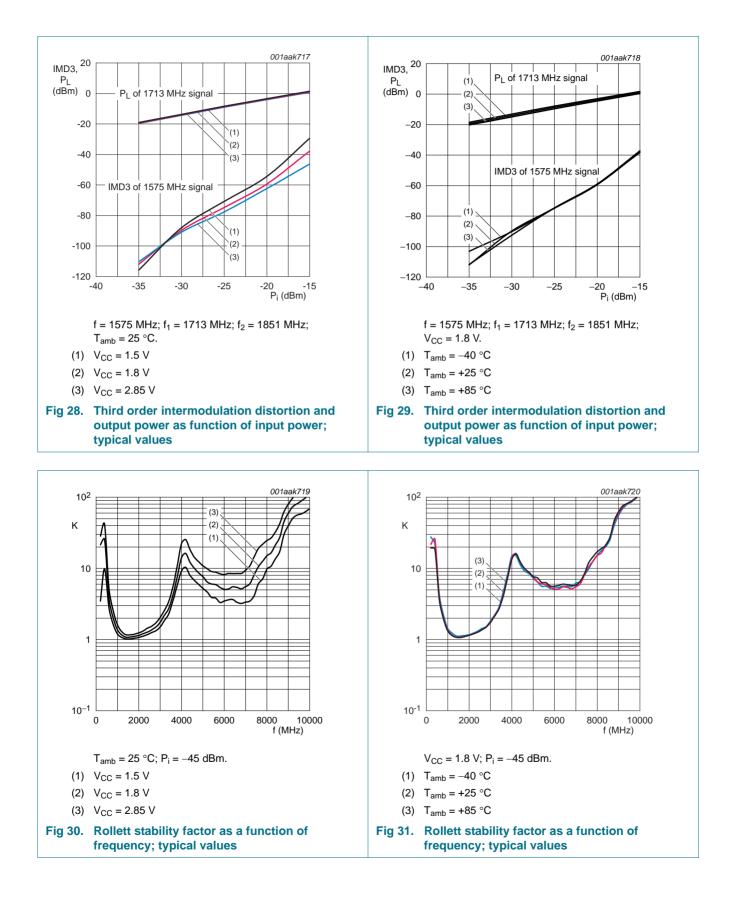






BGU7005

SiGe:C LNA MMIC for GPS, GLONASS, Galileo and Compass



8.2 GPS front-end

The GPS LNA is typically used in a GPS front-end. A GPS front-end application circuit and its characteristics is provided here.

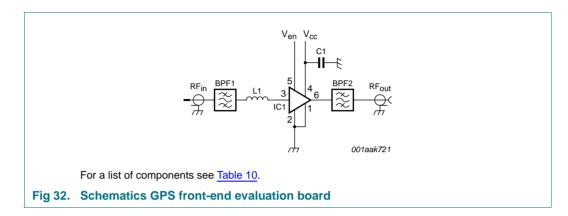


Table 10.List of componentsFor schematics see Figure 32.

	<u> </u>			
Component	Description	Value	Supplier	Remarks
BPF1, BPF2	GPS SAW filter	-	Murata SAFEA1G57KE0F00	Alternatives from Epcos:
				• B9444
				Alternatives from Murata:
				 SAFEA1G57KH0F00
				 SAFEA1G57KB0F00
				Alternatives from Fujitsu:
				• FAR-F6KA-1G5754-L4AA
				• FAR-F6KA-1G5754-L4AJ
C1	decoupling capacitor	1 nF	Various	
IC1	BGU7005	-	NXP	
L1	high quality matching inductor	5.6 nH	Murata LQW15A	

8.3 Characteristics GPS front-end

Table 11. Characteristics GPS front-end

f = 1575 MHz; $V_{CC} = 1.8 \text{ V}$; $V_{ENABLE} \ge 0.8 \text{ V}$; power at LNA input $P_i < -40 \text{ dBm}$; $T_{amb} = 25 \text{ °C}$; input and output matched to 50 Ω ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{CC}	supply voltage	RF input AC coupled	1.5	-	2.85	V
I _{CC}	supply current		-	4.5	-	mA
T _{amb}	ambient temperature		-40	+25	+85	°C
G _p	power gain	power at LNA input P _i < -40 dBm	<u>[1]</u> _	14.5	-	dB
		power at LNA input $P_i = -20 \text{ dBm}$	<u>[1]</u> _	15.5	-	dB
RL _{in}	input return loss	power at LNA input P _i < -40 dBm	<u>[1]</u> _	8.5	-	dB
		power at LNA input $P_i = -20 \text{ dBm}$	<u>[1]</u> _	10.5	-	dB
RL _{out}	output return loss	power at LNA input $P_i < -40 \text{ dBm}$	<u>[1]</u> _	14.5	-	dB
		power at LNA input $P_i = -20 \text{ dBm}$	<u>[1]</u> _	12.5	-	dB

Table 11. Characteristics GPS front-end ...continued

f = 1575 MHz; $V_{CC} = 1.8 \text{ V}$; $V_{ENABLE} \ge 0.8 \text{ V}$; power at LNA input $P_i < -40 \text{ dBm}$; $T_{amb} = 25 \text{ °C}$; input and output matched to 50 Ω ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Мах	Unit
NF	noise figure	power at LNA input P _i < -40 dBm	<u>[1]</u> -	1.8	-	dB
		power at LNA input $P_i = -20 \text{ dBm}$	<u>[1]</u> _	1.9	-	dB
P _{i(1dB)}	input power at 1 dB gain compression	f = 1575 MHz		-8.2		dBm
		f = 806 MHz to 928 MHz	[2]	31		dBm
		f = 1612 MHz to 1909 MHz	[2]	40		dBm
IP3 _i	input third-order intercept point		[3]	64		dBm
α	attenuation	f = 850 MHz	<u>[4]</u> 95	-	-	dBc
		f = 1850 MHz	<u>[4]</u> 90	-	-	dBc
t _{on}	turn-on time		<u>[5]</u> _	-	2	μS
t _{off}	turn-off time		[5] _	-	1	μs

[1] Power at GPS front-end input = power at LNA input + attenuation BPF1.

[2] Out of band.

[3] $f_1 = 1713 \text{ MHz}; f_2 = 1851 \text{ MHz}; P_1 = P_2 = +10 \text{ dBm}.$

[4] Relative to f = 1575 MHz.

[5] Within 10 % of the final gain.

9. Package outline

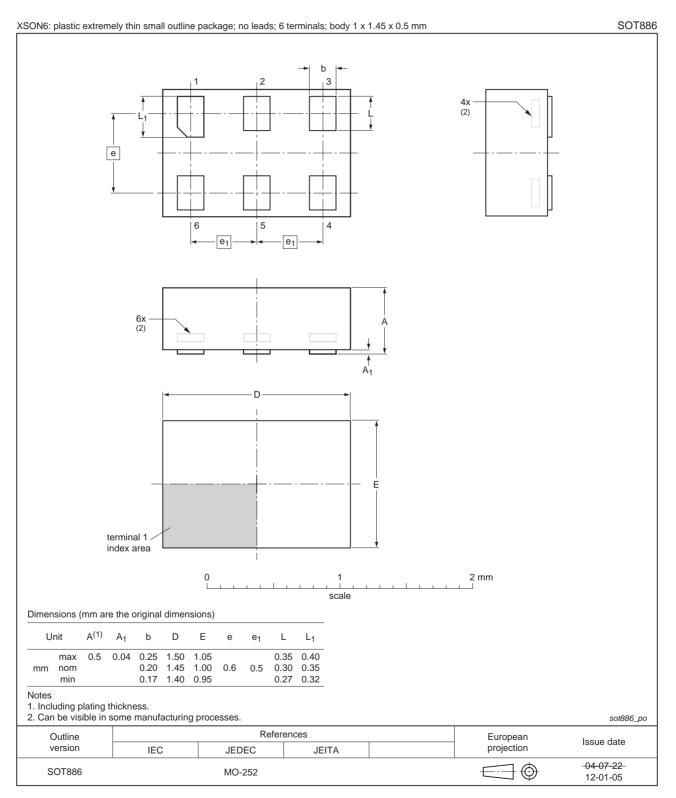


Fig 33. Package outline SOT886 (XSON6)

10. Abbreviations

	Description
Acronym	Description
AC	Alternating Current
ATM	Automated Teller Machine (cash dispenser)
DC	Direct Current
GLONASS	GLObal NAvigation Satellite System
GNSS	Global Navigation Satellite System
GPS	Global Positioning System
HBM	Human Body Model
MMIC	Monolithic Microwave Integrated Circuit
PC	Personal Computer
PCB	Printed Circuit Board
RF	Radio Frequency
SAW	Surface Acoustic Wave
SiGe:C	Silicon Germanium Carbon

11. Revision history

Table 13.Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes	
BGU7005 v.6	20170118	Product data sheet	-	BGU7005 v.5	
Modifications:	 <u>Section 1</u>: added 	GPS1101M according to our new na	aming convention		
BGU7005 v.5	<tbd></tbd>	Product data sheet	-	BGU7005 v.4	
Modifications:	 Added 'Compass 	' to descriptive title			
	Section 1.2 on page	age 1: row 6, changed 2.8.5 V to 3.1	V		
	• Section 1.3 on page 2: updated				
	• Table 1 on page 2, Table 7 on page 4 and Table 8 on page 5: changed value V _{CC} from 2.85 V to 3.1				
	 <u>Table 5 on page 3</u>: several additions and changes 				
	 Figure 8 on page 	8 and Figure 9 on page 8: corrected	d figure titles		
BGU7005 v.4	20110506	Product data sheet	-	BGU7005 v.3	
BGU7005 v.3	20100623	Product data sheet	-	BGU7005_2	
		Due durat data alcant			
BGU7005_2	20100304	Product data sheet	-	BGU7005_1	

12. Legal information

12.1 Data sheet status

Document status[1][2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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